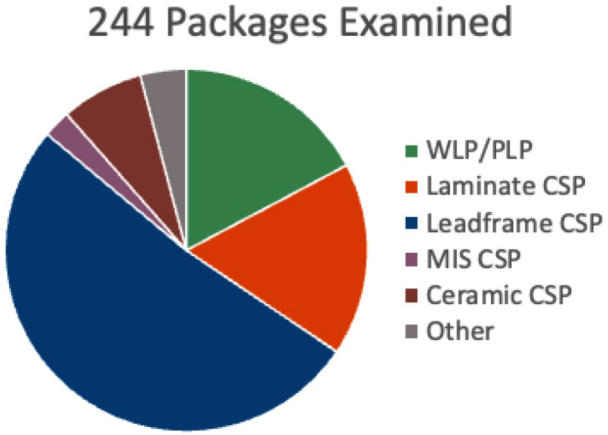
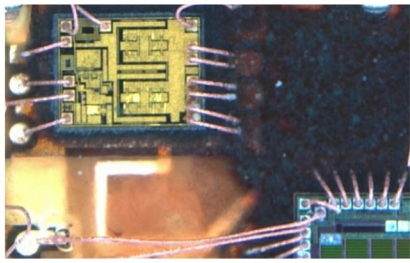
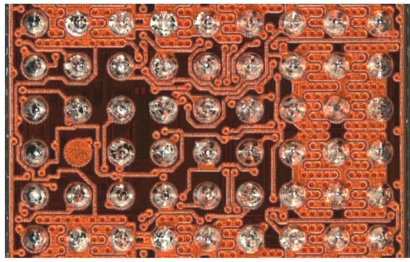


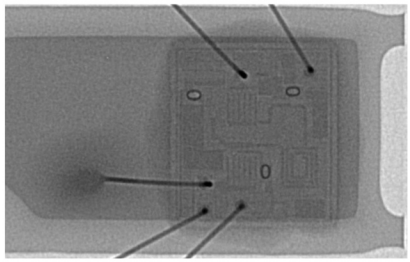
Huawei Mate 60 Pro

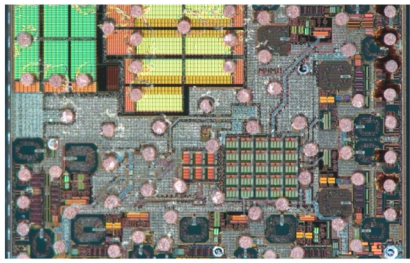
Teardown from TechSearch International, Inc.

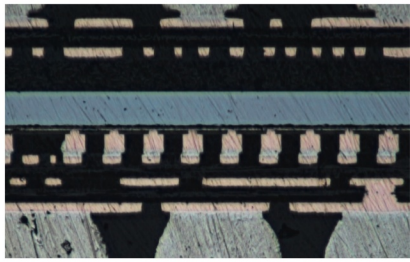


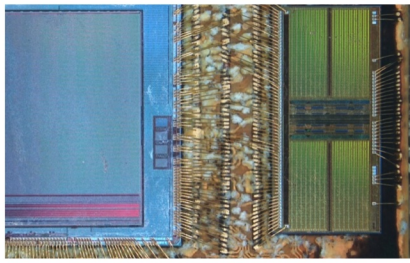












Contents and Highlights

- 335-page report with package quantity summaries, high-resolution photos and x-rays, package dimensions, thermal management material identification
- 23 slides with extra details including PoP and main board cross sections, advanced packaging technology characteristics, and interesting finds
- Deep analysis of the Huawei Kirin 9000S application processor, including layer and Cu pillar metrics from cross sections
- Decapsulation of packages such as RF FEMs from HiSilicon and OnMicro, RF transceivers from Runtech, and satellite baseband processor from Hwa Create Technology
- Nearly 80% of the chips in the phone are from Chinese suppliers

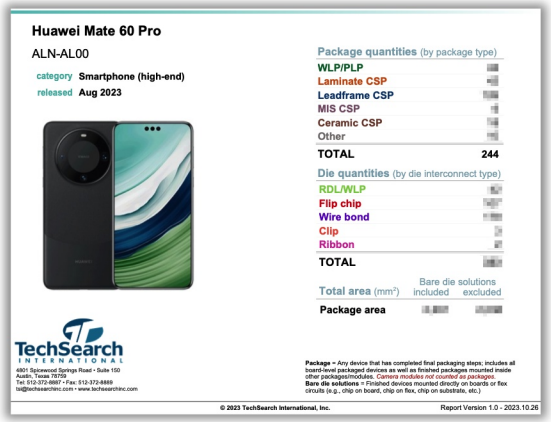
Teardowns backed by 36 years serving as the industry's trusted source for semiconductor packaging trend analysis

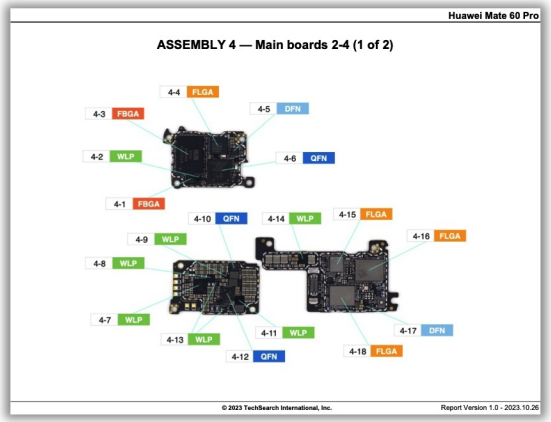
- Examination of all chips with emphasis on assembly and packaging technologies
- Superb quality photographs and x-ray images
- Both the packages and the die within are identified and characterized
- Detailed construction analysis of key chips and packages

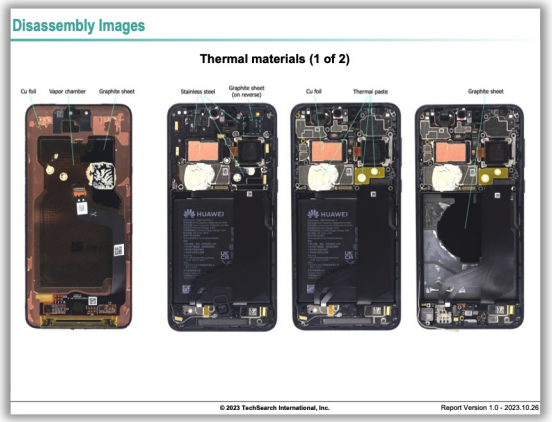
TechSearch INTERNATIONAL

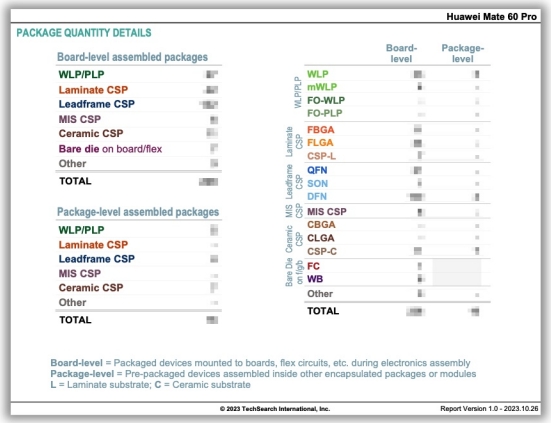
techsearchinc.com • +1-512-372-8887

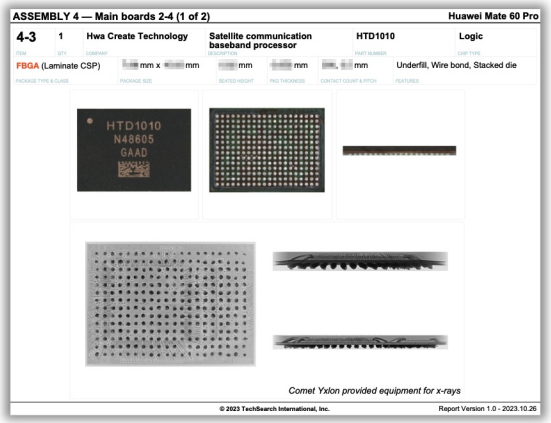
Sample pages from the report and slides

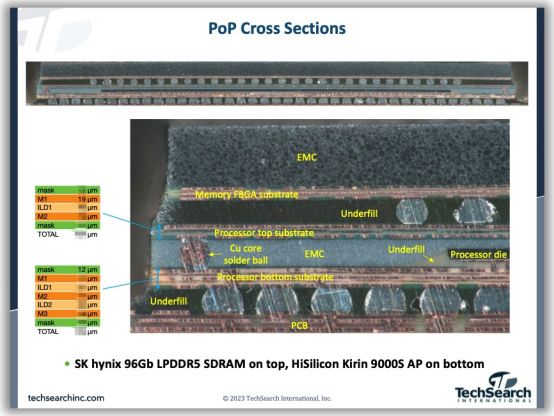


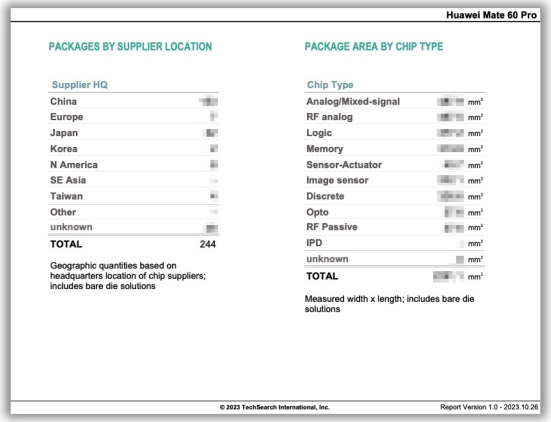


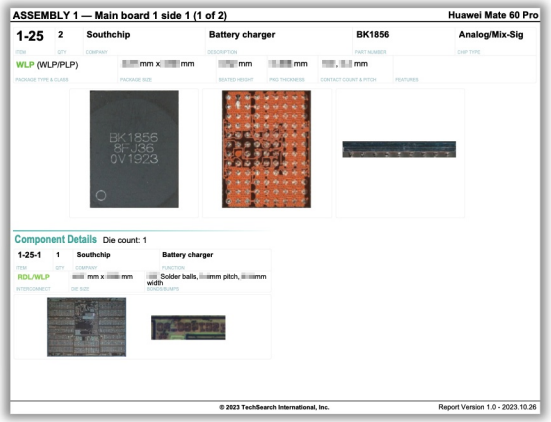


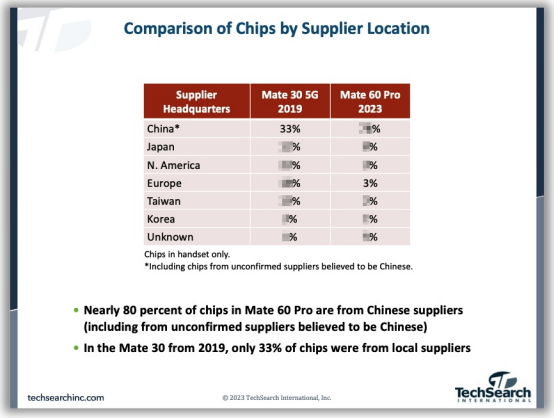












For pricing, please call +1-512-372-8887